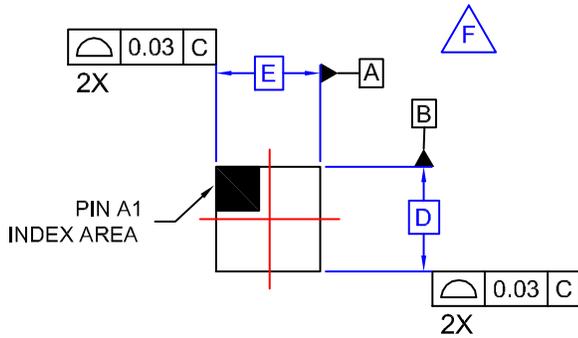
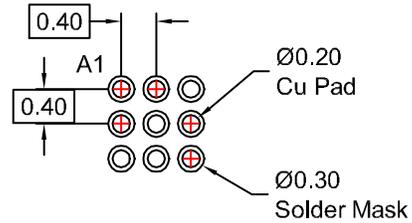


WLCSP9 1.29x1.27x0.586
CASE 567QF
ISSUE O

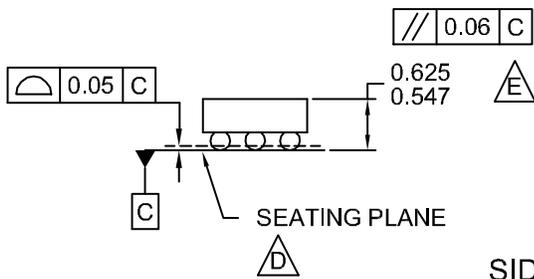
DATE 31 OCT 2016



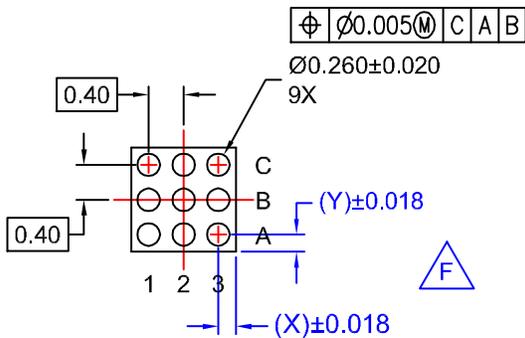
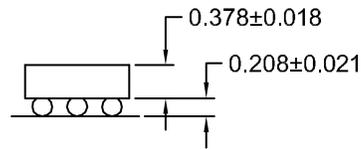
TOP VIEW



LAND PATTERN RECOMMENDATION
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
-  D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
-  E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
-  F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP9 1.29x1.27x0.586	PAGE 1 OF 1

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